

2.0A/1.5A LDO REGULATOR

NO. EA-125-090202

OUTLINE

The R1171x Series are CMOS-based positive voltage regulator ICs. The R1171x Series have features of low dropout voltage, high output voltage accuracy, low consumption current. Each of these ICs consists of a voltage reference unit, an error amplifier, resistor net for setting output voltage, a current limit circuit at short mode, a chip enable circuit, and thermal shutdown circuit. The output voltage of R1171 is fixed in the IC.

Low consumption current by the merit of CMOS process and built-in transistors with low ON-resistance make low dropout voltage and chip enable function prolongs the battery life. These regulators are remarkable improvement on the current regulators in terms of input transient response, and load transient response.

Thus, the R1171x Series are suitable for various power sources.

Since the packages for these ICs are high wattage HSOP-6J package, TO-252-5-P1, high density mounting of the ICs on boards is possible.

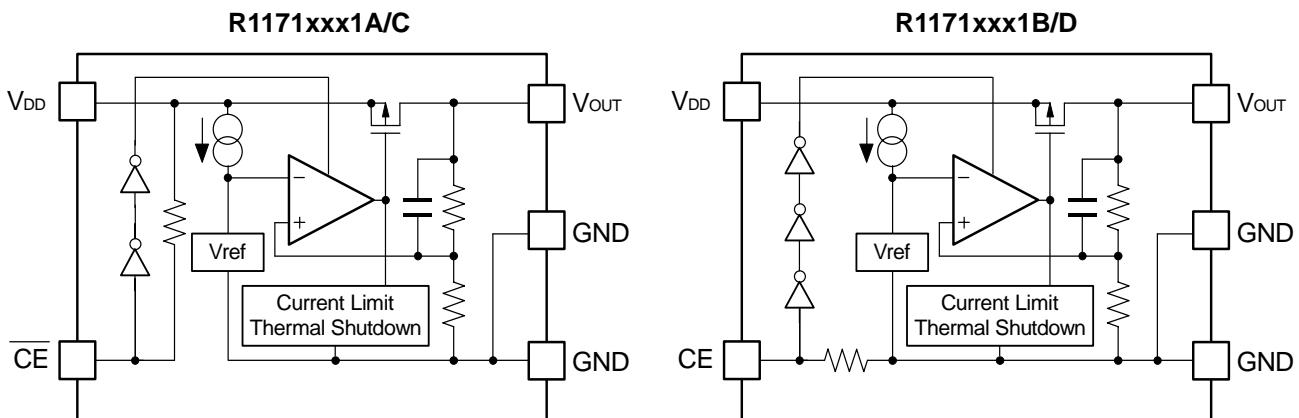
FEATURES

- Supply Current Typ. 130 μ A
- Standby Current Typ. 0.1 μ A
- Output Current Min. 1.5A ($V_{IN}=V_{OUT}+1.0V$, R1171Sxx1A/B)
Min. 2.0A ($V_{IN}=V_{OUT}+1.0V$, R1171Jxx1C/D)
- Input Voltage 2.1V to 6.0V
- Output Voltage 1.5V to 5.0V (R1171Sxx1A/B)
1.8V to 5.0V (R1171Jxx1C/D)
- Output Voltage Accuracy $\pm 2.0\%$
- Dropout Voltage Typ. 0.09V ($V_{OUT}=3.0V$, $I_{OUT}=300mA$)
- Temperature-drift Coefficient of Output Voltage Typ. $\pm 100ppm/^{\circ}C$
- Line Regulation Typ. 0.05%/V
- Packages HSOP-6J, TO-252-5-P1
- Built-in Current Limit Circuit
- Built-in Thermal Shutdown Circuit
- Ceramic capacitor for phase compensation $C_{IN}=C_{OUT}=\text{Ceramic } 10\mu F$ ($V_{OUT}<1.8V$)
 $C_{IN}=C_{OUT}=\text{Ceramic } 4.7\mu F$ ($V_{OUT} \geq 1.8V$)

APPLICATIONS

- Local Power source for Notebook PC.
- Local Power source for portable appliances, cameras, and videos.
- Local Power source for equipment of battery-use.
- Local Power source for home appliances.

BLOCK DIAGRAMS



SELECTION GUIDE

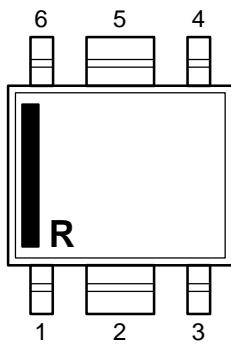
The output voltage, the chip-enable polarity, the taping type can be selected at the user's request.
The selection can be made with the part number as follows;

R1171xxx1x-XX-X ←Part Number
 ↑↑ ↑↑ ↑
 a b c d e

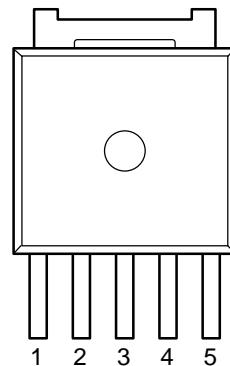
Code	Contents
a	Package Type; S: HSOP-6J J: TO-252-5-P1
b	Designation of Output Voltage (V_{OUT}) Stepwise setting with 0.1V increment in the range from 1.5V to 5.0V (A/B version), from 1.8V to 5.0V (C/D version). Exception; 1.85V Type: R1171x181x5, 2.85V type: R1171x281x5-xx
c	Designation of option; A: Built-in Chip Enable Circuit, Active at "L" (Output Current :Min.1.5A) B: Built-in Chip Enable Circuit, Active at "H" (Output Current :Min.1.5A) C: Built-in Chip Enable Circuit, Active at "L" (Output Current :Min.2.0A) D: Built-in Chip Enable Circuit, Active at "H" (Output Current :Min.2.0A)
d	Designation of Taping Type; E2: HSOP-6J T1: TO-252-5-P1 (Refer to Taping Specifications)
e	Designation of composition of pin plating: -F: Lead free solder plating (HSOP-6J, TO-252-5-P1)

PIN CONFIGURATIONS

- HSOP-6J



- TO-252-5-P1



PIN DESCRIPTIONS

- HSOP-6J

Pin No.	Symbol	Description
1	V _{OUT}	Output Pin
2	GND	Ground Pin
3	\overline{CE} or CE	Chip Enable Pin
4	NC	No Connection
5	GND	Ground Pin
6	V _{DD}	Input Pin

- TO-252-5-P1

Pin No.	Symbol	Description
1	V _{OUT}	Output Pin
2	\overline{CE} or CE	Chip Enable Pin
3	GND	Ground Pin
4	GND	Ground Pin
5	V _{DD}	Input Pin

*) No.3 and No.4 pins must be wired short each other and connected to the GND plane when it is mounted on board.

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating	Unit
V _{IN}	Input Voltage	7.0	V
V _{CE}	Input Voltage (\overline{CE} or CE Input Pin)	-0.3 to V _{IN} +0.3	V
V _{OUT}	Output Voltage	-0.3 to V _{IN} +0.3	V
I _{OUT}	Output Current	3.5	A
P _D	Power Dissipation (HSOP-6J) ^{*1}	1700	mW
	Power Dissipation (TO-252-5-P1) ^{*1}	1900	
T _{opt}	Operating Temperature	-40 to 85	°C
T _{stg}	Storage Temperature	-55 to 125	°C

*1) For Power Dissipation, please refer to PACKAGE INFORMATION to be described.

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field.

The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS (ELECTRICAL CHARACTERISTICS)

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge.

And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

ELECTRICAL CHARACTERISTICS

• R1171Sxx1A

Topt=25°C

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V _{OUT}	Output Voltage	V _{IN} -V _{OUT} =1.0V, I _{OUT} =200mA	>0.98		<1.02	V
I _{OUT}	Output Current	V _{IN} -V _{OUT} =1.0V	1.5			A
ΔV _{OUT} / ΔI _{OUT}	Load Regulation	V _{IN} -V _{OUT} =1.0V 1mA ≤ I _{OUT} ≤ 300mA		10	60	mV
V _{DIF}	Dropout Voltage	I _{OUT} =300mA	1.5 ≤ V _{OUT} <1.6	0.16	0.35	V
			1.6 ≤ V _{OUT} <1.7	0.14	0.32	
			1.7 ≤ V _{OUT} <1.8	0.13	0.28	
			1.8 ≤ V _{OUT} <2.0	0.12	0.24	
			2.0 ≤ V _{OUT} <2.5	0.10	0.21	
			2.5 ≤ V _{OUT} ≤ 5.0	0.09	0.18	
I _{SS}	Supply Current	V _{IN} -V _{OUT} =1.0V, V _{CE} =0V		130	320	μA
I _{standby}	Standby Current	V _{IN} -V _{OUT} =1.0V, V _{IN} =V _{CE}		0.1	2.0	μA
ΔV _{OUT} /ΔV _{IN}	Line Regulation	I _{OUT} =200mA		Refer to the following table		
RR	Ripple Rejection	f=1kHz, Ripple 0.5Vp-p				
V _{IN}	Input Voltage		2.1		6.0	V
ΔV _{OUT} / ΔT _{opt}	Output Voltage Temperature Coefficient	I _{OUT} =10mA -40°C ≤ T _{opt} ≤ 85°C		±100		ppm/°C
I _{lim}	Short Current Limit	V _{OUT} =0V		200		mA
R _{Pu}	Pull-up resistance for CE pin		2.5	5.0	10.0	MΩ
V _{CEH}	CE Input Voltage "H"		1.2		V _{IN}	V
V _{CEL}	CE Input Voltage "L"		0		0.25	V
T _{TSD}	Thermal Shutdown Detector Threshold Temperature	Junction Temperature		150		°C
T _{TSR}	Thermal Shutdown Released Temperature	Junction Temperature		120		°C

• Line Regulation by Output Voltage

Topt=25°C

Output Voltage V _{OUT} (V)	Line Regulation ΔV _{OUT} /ΔV _{IN} (%/V)		
	Condition	Typ.	Max.
1.5 ≤ V _{OUT} < 1.6	I _{OUT} =200mA, 2.1V ≤ V _{IN} ≤ 6.0V	0.05	0.30
1.6 ≤ V _{OUT} ≤ 5.0	I _{OUT} =200mA, V _{OUT} +0.5V ≤ V _{IN} ≤ 6.0V		

• Ripple Rejection by Output Voltage

Topt=25°C

Output Voltage V _{OUT} (V)	Ripple Rejection RR (dB)	
	Condition	Typ.
1.5 ≤ V _{OUT} < 4.7	f=1kHz, Ripple 0.5Vp-p, V _{IN} -V _{OUT} =1.0V	50
4.7 ≤ V _{OUT} ≤ 5.0	f=1kHz, Ripple 0.5Vp-p, V _{IN} =5.75V	

R1171x

- R1171Sxx1B

T_{opt}=25°C

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V _{OUT}	Reference Voltage for Adjustable Voltage Regulator	V _{IN} -V _{OUT} =1.0V I _{OUT} =200mA	>0.98		<1.02	V
I _{OUT}	Output Current	V _{IN} -V _{OUT} =1.0V	1.5			A
ΔV _{OUT} / ΔI _{OUT}	Load Regulation	V _{IN} -V _{OUT} =1.0V 1mA ≤ I _{OUT} ≤ 300mA		10	60	mV
V _{DIF}	Dropout Voltage	I _{OUT} =300mA	1.5 ≤ V _{OUT} <1.6		0.16	0.35
			1.6 ≤ V _{OUT} <1.7		0.14	0.32
			1.7 ≤ V _{OUT} <1.8		0.13	0.28
			1.8 ≤ V _{OUT} <2.0		0.12	0.24
			2.0 ≤ V _{OUT} <2.5		0.10	0.21
			2.5 ≤ V _{OUT} ≤ 5.0		0.09	0.18
I _{SS}	Supply Current	V _{IN} -V _{OUT} =1.0V, V _{CE} =V _{IN}		130	320	μA
I _{standby}	Standby Current	V _{IN} -V _{OUT} =1.0V, V _{CE} =0V		0.1	2.0	μA
ΔV _{OUT} /ΔV _{IN}	Line Regulation	I _{OUT} =200mA		Refer to the following table		
RR	Ripple Rejection	f=1kHz, Ripple 0.5Vp-p				
V _{IN}	Input Voltage		2.1		6.0	V
ΔV _{OUT} / ΔT _{opt}	Output Voltage Temperature Coefficient	I _{OUT} =10mA -40°C ≤ T _{opt} ≤ 85°C		±100		ppm/°C
I _{lim}	Short Current Limit	V _{OUT} =0V		200		mA
R _{PD}	Pull-down resistance for CE pin		2.5	5.0	10.0	MΩ
V _{CEH}	CE Input Voltage "H"		1.2		V _{IN}	V
V _{CEL}	CE Input Voltage "L"		0		0.25	V
T _{TSD}	Thermal Shutdown Detector Threshold Temperature	Junction Temperature		150		°C
T _{TSR}	Thermal Shutdown Released Temperature	Junction Temperature		120		°C

- Line Regulation by Output Voltage

T_{opt}=25°C

Output Voltage V _{OUT} (V)	Line Regulation ΔV _{OUT} /ΔV _{IN} (%/V)		
	Condition	Typ.	Max.
1.5 ≤ V _{OUT} < 1.6	I _{OUT} =200mA, 2.1V ≤ V _{IN} ≤ 6.0V	0.05	0.30
1.6 ≤ V _{OUT} ≤ 5.0	I _{OUT} =200mA, V _{OUT} +0.5V ≤ V _{IN} ≤ 6.0V		

- Ripple Rejection by Output Voltage

T_{opt}=25°C

Output Voltage V _{OUT} (V)	Ripple Rejection RR (dB)	
	Condition	Typ.
1.5 ≤ V _{OUT} < 4.7	f=1kHz, Ripple 0.5Vp-p, V _{IN} -V _{OUT} =1.0V	50
4.7 ≤ V _{OUT} ≤ 5.0	f=1kHz, Ripple 0.5Vp-p, V _{IN} =5.75V	

- R1171Jxx1C

Topt=25°C

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V _{OUT}	Output Voltage	V _{IN} -V _{OUT} =1.0V I _{OUT} =200mA	>0.98		<1.02	V
I _{OUT}	Output Current	V _{IN} -V _{OUT} =1.0V	2.0			A
ΔV _{OUT} / ΔI _{OUT}	Load Regulation	V _{IN} -V _{OUT} =1.0V 1mA ≤ I _{OUT} ≤ 300mA		10	60	mV
V _{DIF}	Dropout Voltage	I _{OUT} =300mA	1.8 ≤ V _{OUT} <2.0		0.12	0.24
			2.0 ≤ V _{OUT} <2.5		0.10	0.21
			2.5 ≤ V _{OUT} ≤ 5.0		0.09	0.18
I _{SS}	Supply Current	V _{IN} -V _{OUT} =1.0V, V _{CE} =0V		130	320	μA
I _{standby}	Standby Current	V _{IN} -V _{OUT} =1.0V, V _{IN} =V _{CE}		0.1	2.0	μA
ΔV _{OUT} / ΔV _{IN}	Line Regulation	I _{OUT} =200mA V _{OUT} +0.5V ≤ V _{IN} ≤ 6V		0.05	0.30	%/V
RR	Ripple Rejection	f=1kHz, Ripple 0.5Vp-p	Refer to the following table			
V _{IN}	Input Voltage		2.1		6.0	V
ΔV _{OUT} / ΔTopt	Output Voltage Temperature Coefficient	I _{OUT} =10mA -40°C ≤ Topt ≤ 85°C		±100		ppm/°C
I _{lim}	Short Current Limit	V _{OUT} =0V		200		mA
R _{PU}	Pull-up resistance for \overline{CE} pin		2.5	5.0	10.0	MΩ
V _{CEH}	\overline{CE} Input Voltage "H"		1.2		V _{IN}	V
V _{CEL}	\overline{CE} Input Voltage "L"		0		0.25	V
T _{TSD}	Thermal Shutdown Detector Threshold Temperature	Junction Temperature		150		°C
T _{TSR}	Thermal Shutdown Released Temperature	Junction Temperature		120		°C

- Ripple Rejection by Output Voltage

Topt=25°C

Output Voltage V _{OUT} (V)	Ripple Rejection RR (dB)	
	Condition	Typ.
1.8 ≤ V _{OUT} < 4.7	f=1kHz, Ripple 0.5Vp-p, V _{IN} -V _{OUT} =1.0V	50
4.7 ≤ V _{OUT} ≤ 5.0	f=1kHz, Ripple 0.5Vp-p, V _{IN} =5.75V	

R1171x

• R1171Jxx1D

Topt=25°C

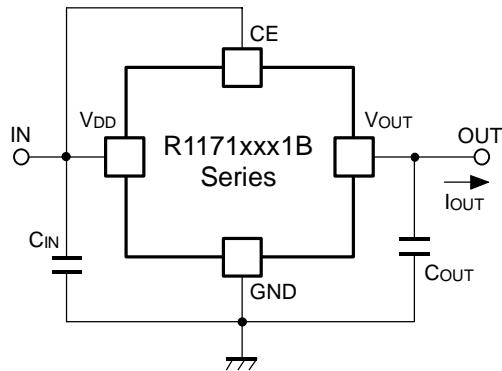
Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V _{OUT}	Reference Voltage for Adjustable Voltage Regulator	V _{IN} -V _{OUT} =1.0V I _{OUT} =200mA	>0.98		<1.02	V
I _{OUT}	Output Current	V _{IN} -V _{OUT} =1.0V	2.0			A
ΔV _{OUT} / ΔI _{OUT}	Load Regulation	V _{IN} -V _{OUT} =1.0V 1mA ≤ I _{OUT} ≤ 300mA		10	60	mV
V _{DIF}	Dropout Voltage	I _{OUT} =300mA	1.8 ≤ V _{OUT} <2.0		0.12	0.24
			2.0 ≤ V _{OUT} <2.5		0.10	0.21
			2.5 ≤ V _{OUT} ≤ 5.0		0.09	0.18
I _{SS}	Supply Current	V _{IN} -V _{OUT} =1.0V, V _{CE} =V _{IN}		130	320	μA
I _{standby}	Standby Current	V _{IN} -V _{OUT} =1.0V, V _{CE} =0V		0.1	2.0	μA
ΔV _{OUT} / ΔV _{IN}	Line Regulation	I _{OUT} =200mA V _{OUT} +0.5V ≤ V _{IN} ≤ 6V		0.05	0.30	%/V
RR	Ripple Rejection	f=1kHz, Ripple 0.5Vp-p	Refer to the following table			
V _{IN}	Input Voltage		2.1		6.0	V
ΔV _{OUT} / ΔT _{opt}	Output Voltage Temperature Coefficient	I _{OUT} =10mA -40°C ≤ Topt ≤ 85°C		±100		ppm/°C
I _{lim}	Short Current Limit	V _{OUT} =0V		200		mA
R _{PD}	Pull-down resistance for CE pin		2.5	5.0	10.0	MΩ
V _{CEH}	CE Input Voltage "H"		1.2		V _{IN}	V
V _{CEL}	CE Input Voltage "L"		0		0.25	V
T _{TSD}	Thermal Shutdown Detector Threshold Temperature	Junction Temperature		150		°C
T _{TSR}	Thermal Shutdown Released Temperature	Junction Temperature		120		°C

• Ripple Rejection by Output Voltage

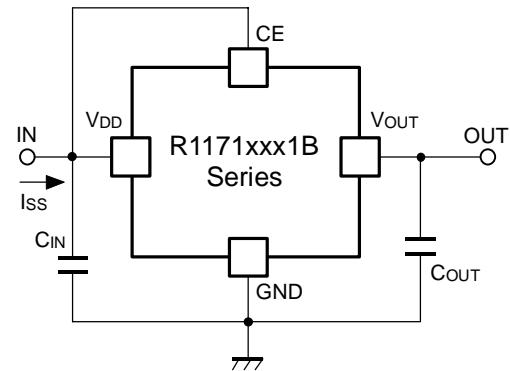
Topt=25°C

Output Voltage V _{OUT} (V)	Ripple Rejection RR (dB)	
	Condition	Typ.
1.8 ≤ V _{OUT} < 4.7	f=1kHz, Ripple 0.5Vp-p, V _{IN} -V _{OUT} =1.0V	50
4.7 ≤ V _{OUT} ≤ 5.0	f=1kHz, Ripple 0.5Vp-p, V _{IN} =5.75V	

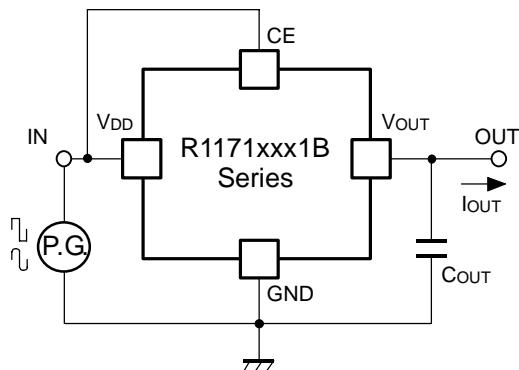
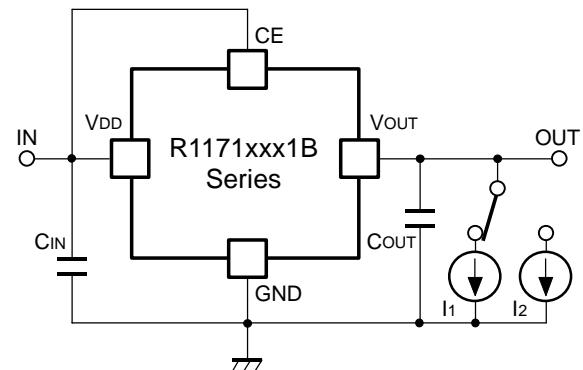
TEST CIRCUITS



Standard Test Circuit



Supply Current Test Circuit

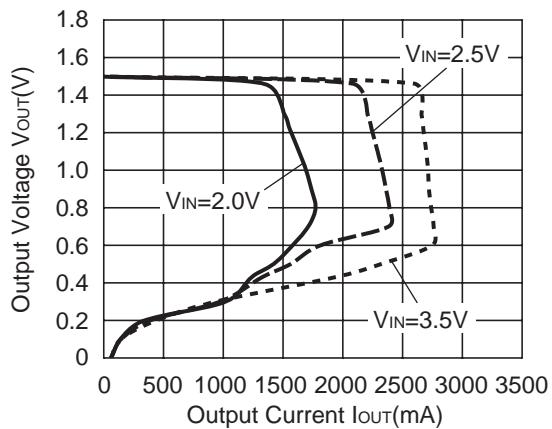
Test Circuit for Ripple Rejection,
Input Transient Response

Test Circuit for Load Transient Response

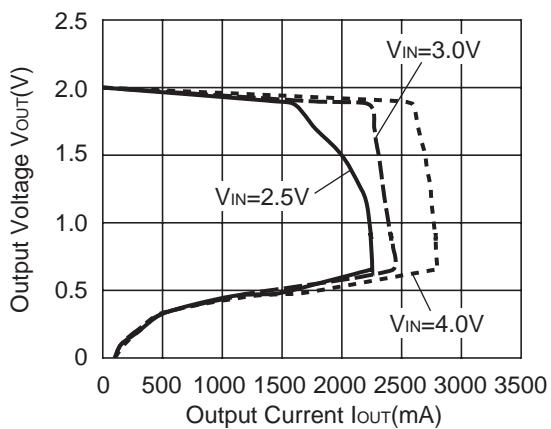
TYPICAL CHARACTERISTICS

1) Output Voltage vs. Output Current ($T_{opt}=25^{\circ}\text{C}$)

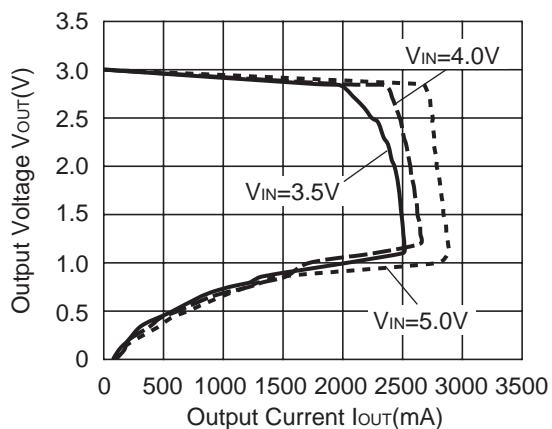
R1171S151x



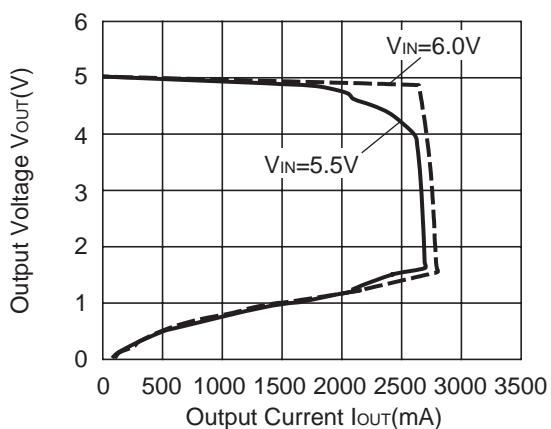
R1171S201x



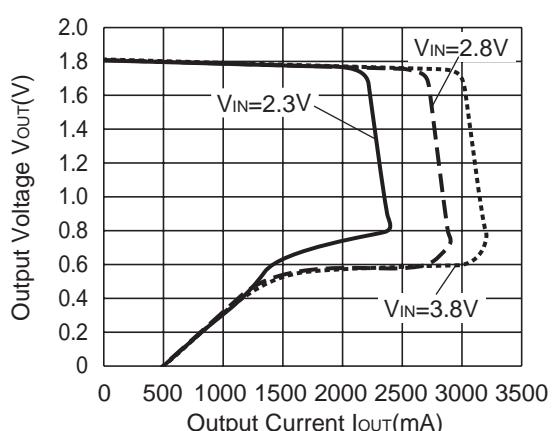
R1171S301x



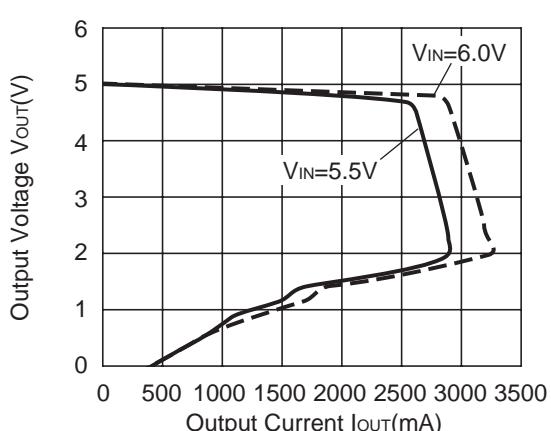
R1171S501x



R1171J181x

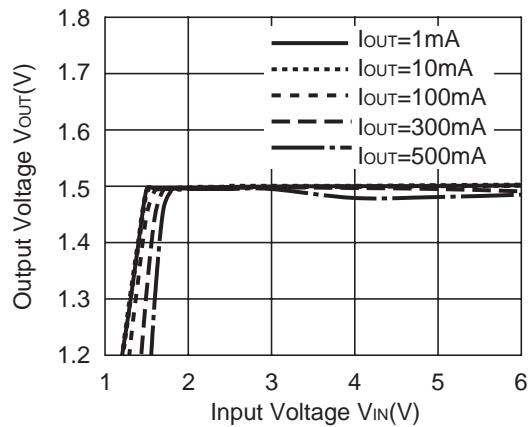


R1171J501x

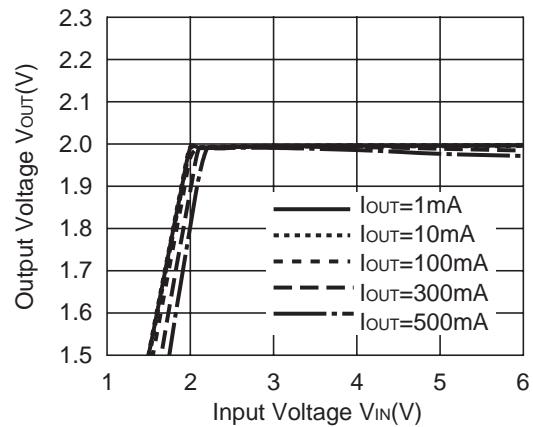


2) Output Voltage vs. Input Voltage ($T_{opt}=25^{\circ}\text{C}$)

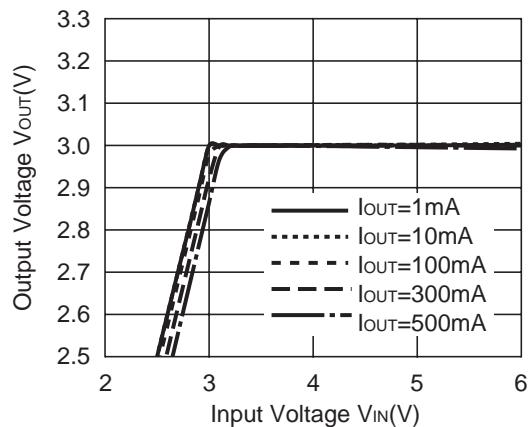
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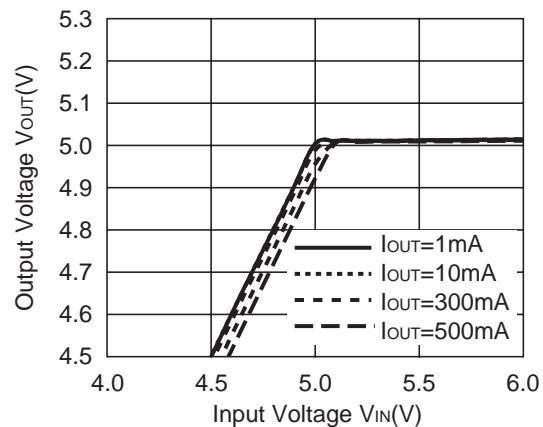
R1171x201B



R1171x301B

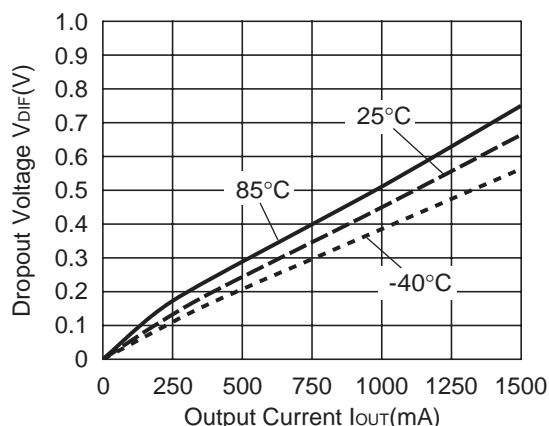


R1171x501B

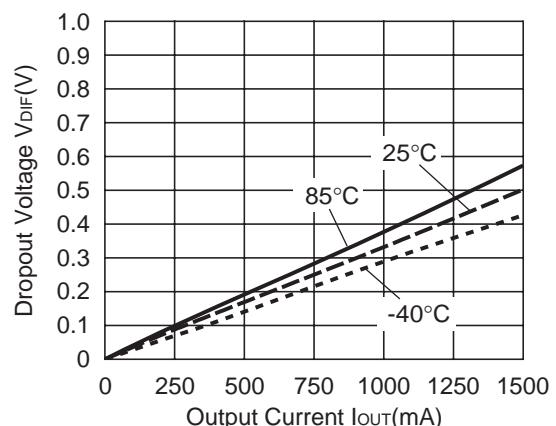


3) Dropout Voltage vs. Output Current

R1171S151x

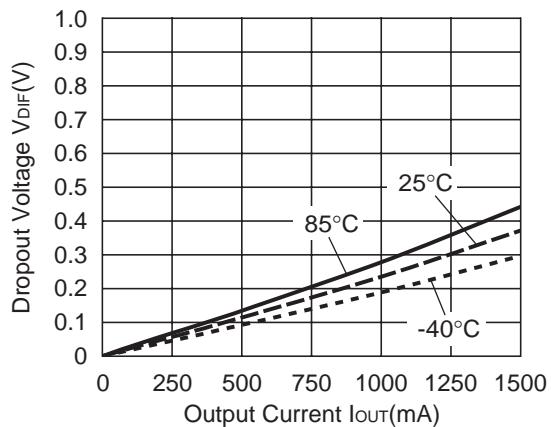


R1171S201x

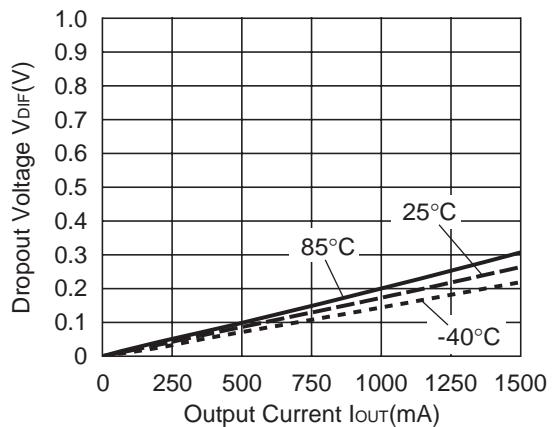


R1171x

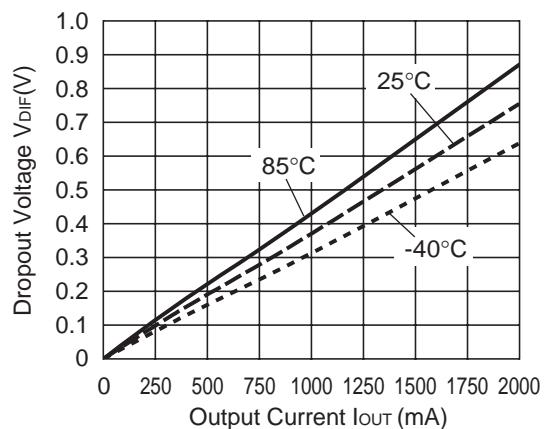
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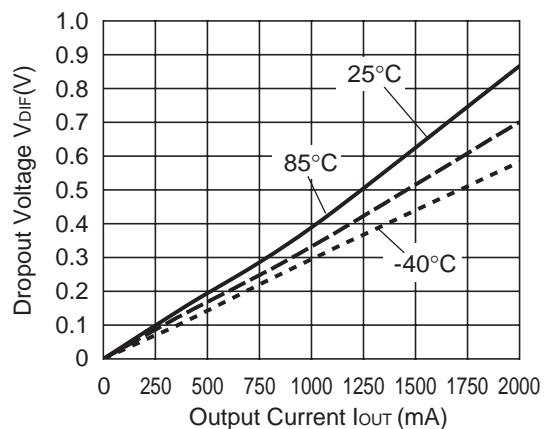
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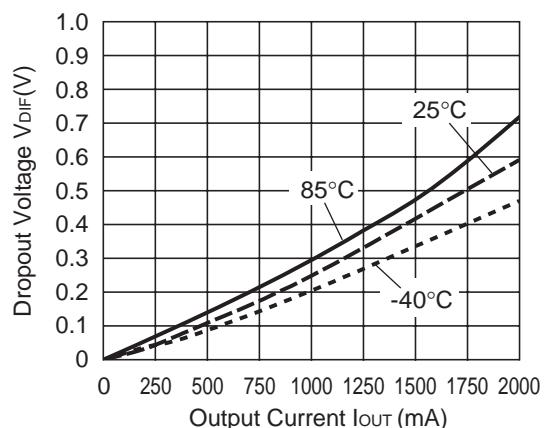
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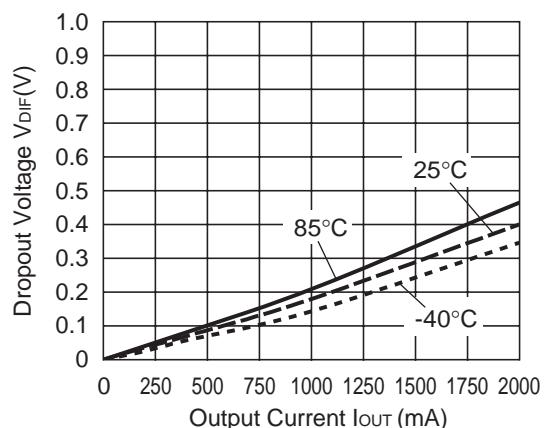
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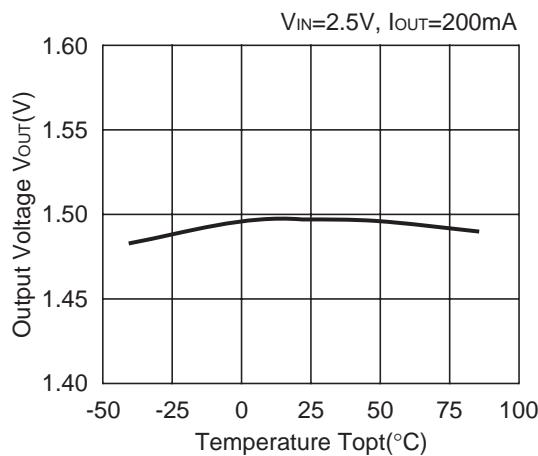
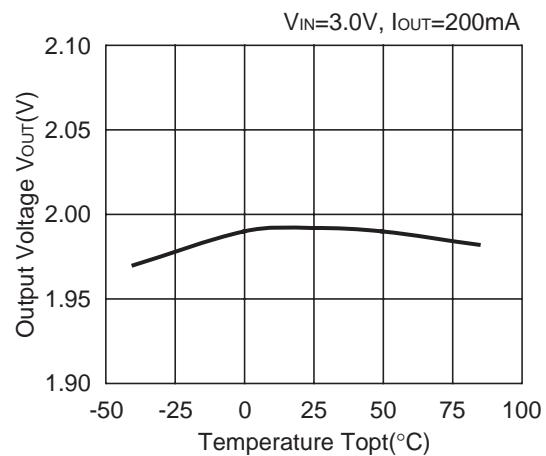
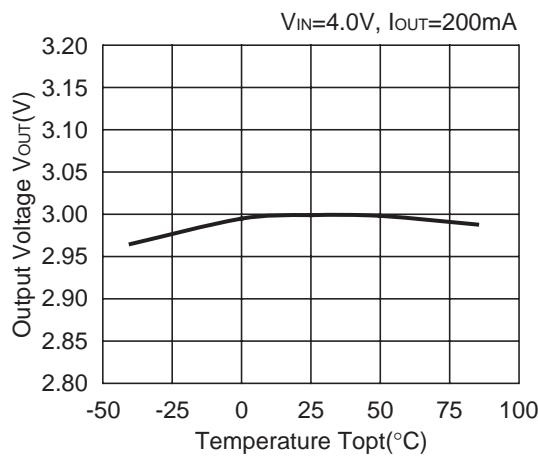
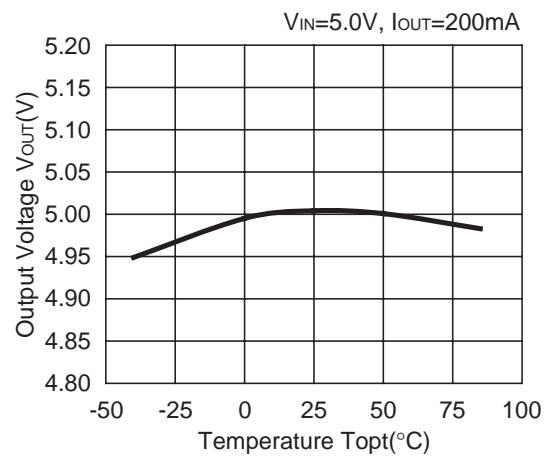
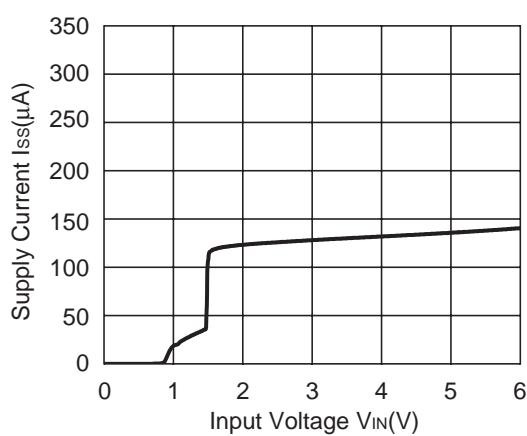
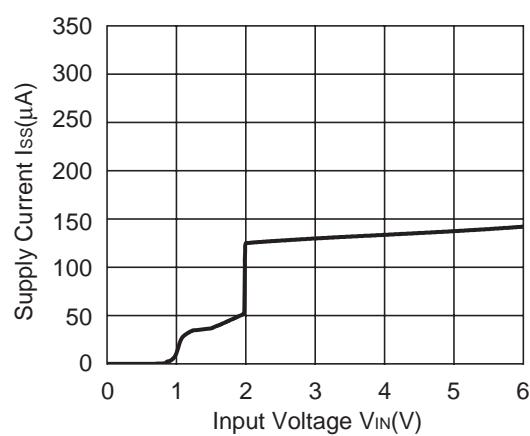


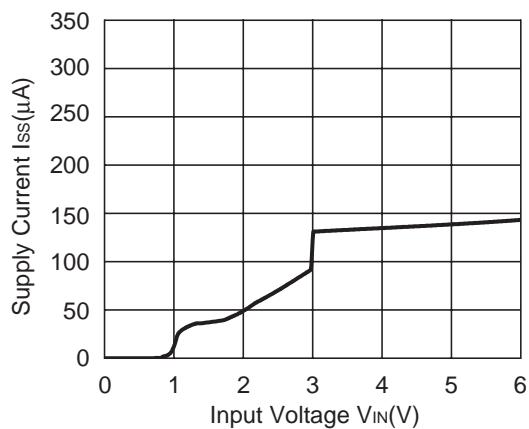
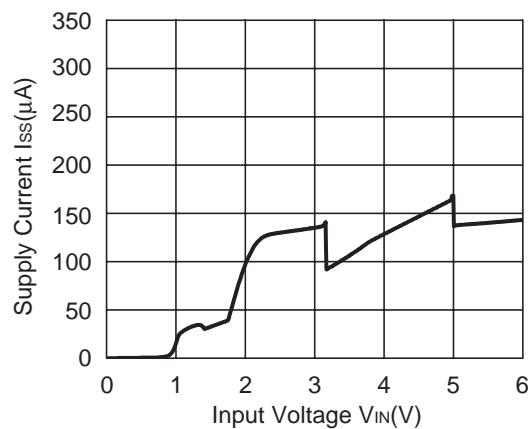
R1171J301x



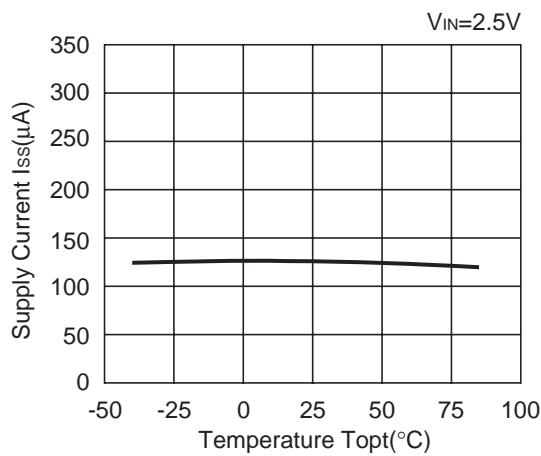
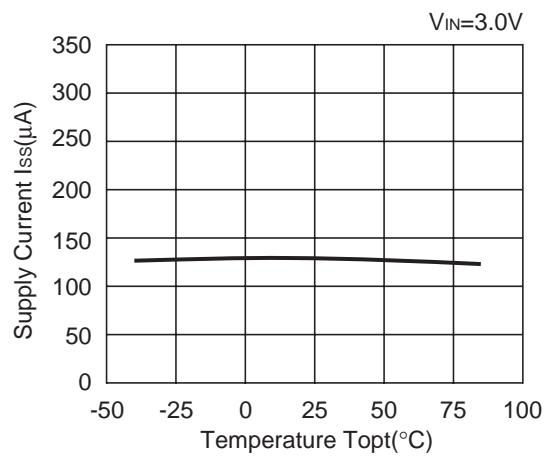
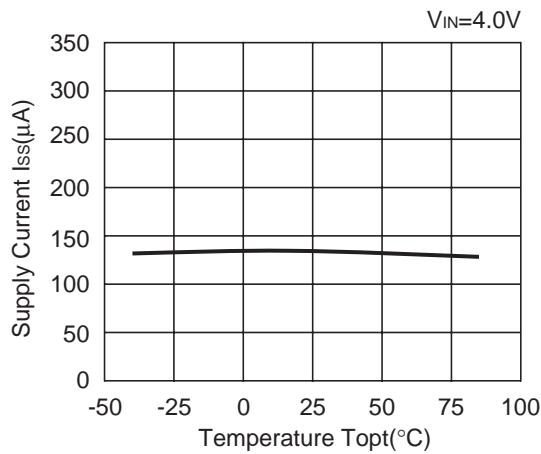
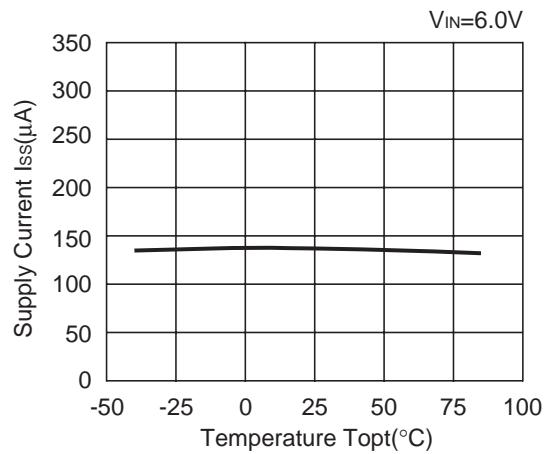
R1171J501x



4) Output Voltage vs. Temperature**R1171x151B****R1171x201B****R1171x301B****R1171x501B****5) Supply Current vs. Input Voltage ($T_{opt}=25^{\circ}C$)****R1171x151B****R1171x201B**

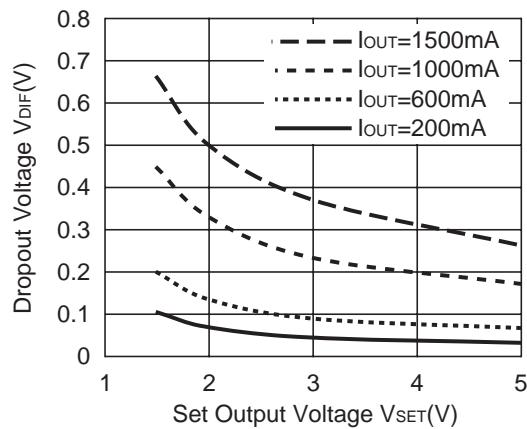
R1171x301B**R1171x501B**

6) Supply Current vs. Temperature

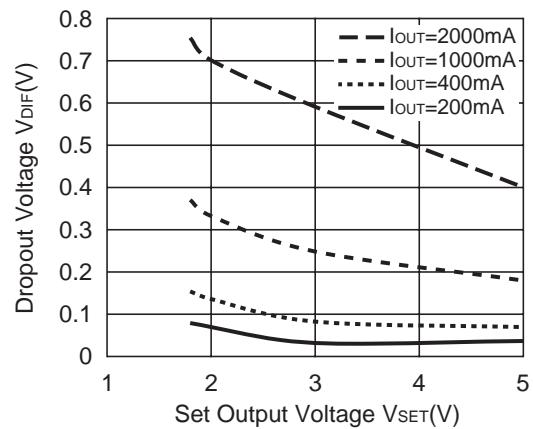
R1171x151B**R1171x201B****R1171x301B****R1171x501B**

7) Dropout Voltage vs. Set Output Voltage ($T_{OPT}=25^{\circ}\text{C}$)

R1171Sxx1x

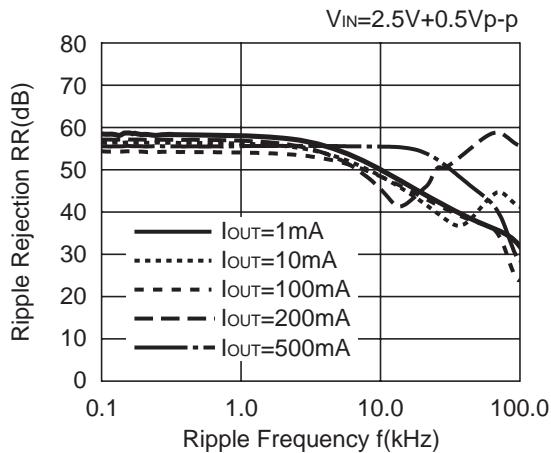


R1171Jxx1x

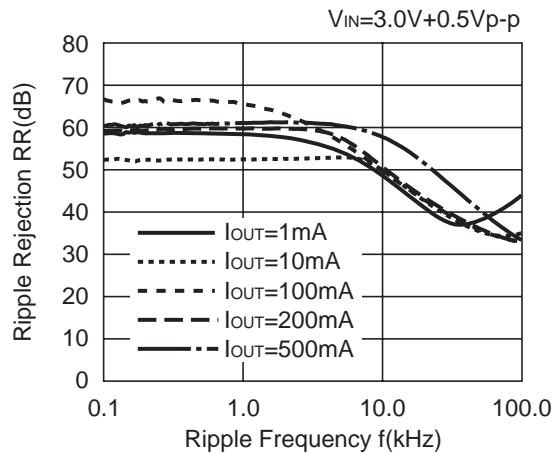


8) Ripple Rejection vs. Frequency

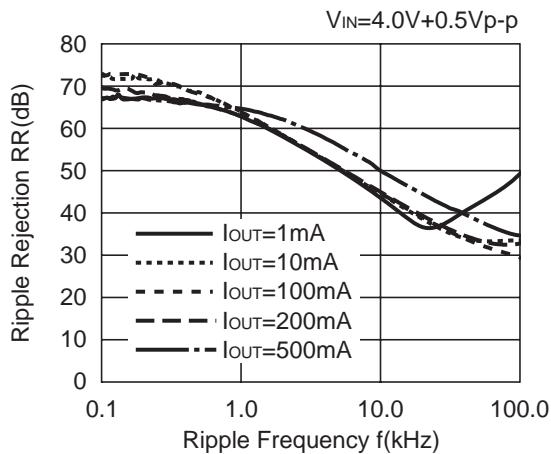
R1171x151B



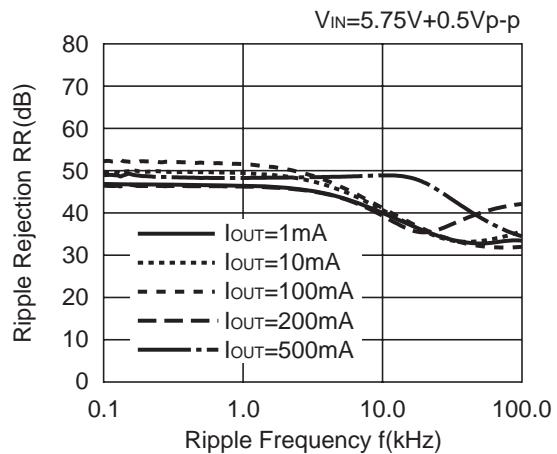
R1171x201B

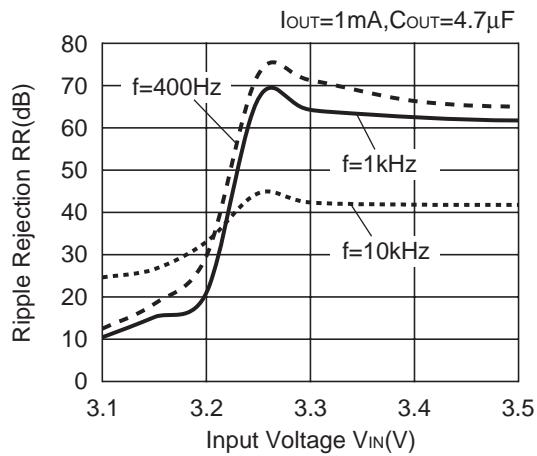
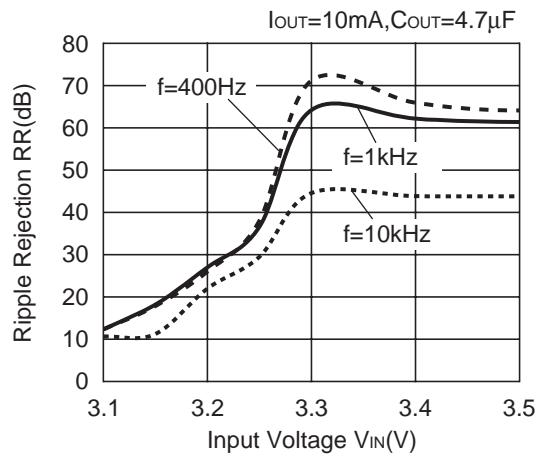
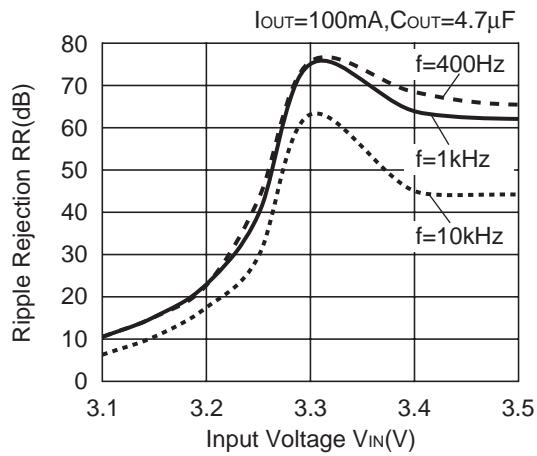
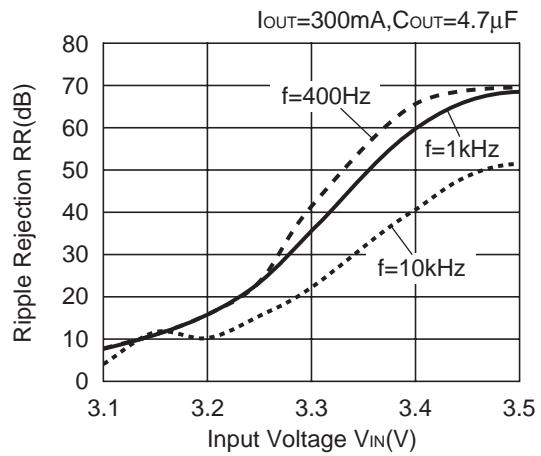
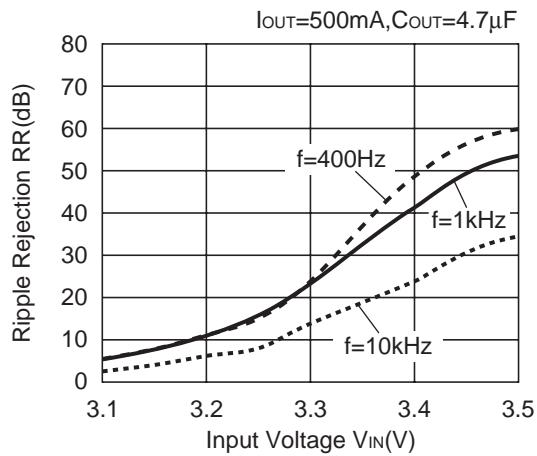


R1171x301B



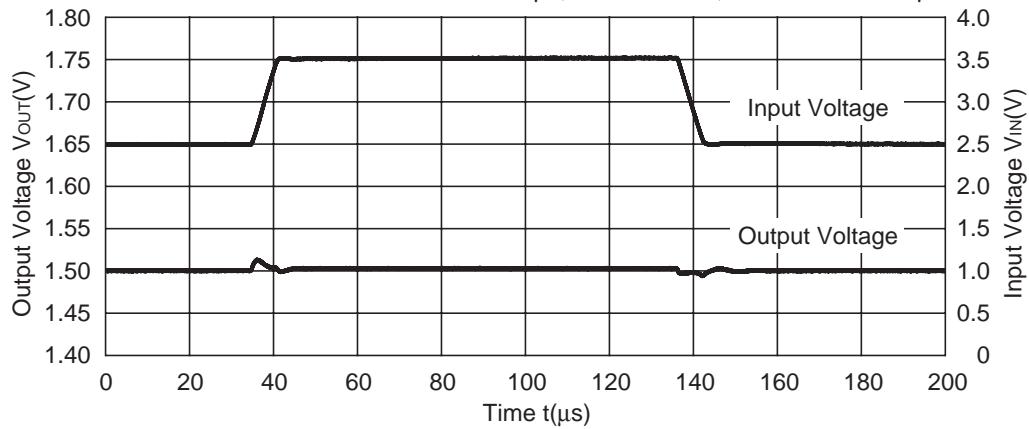
R1171x501B



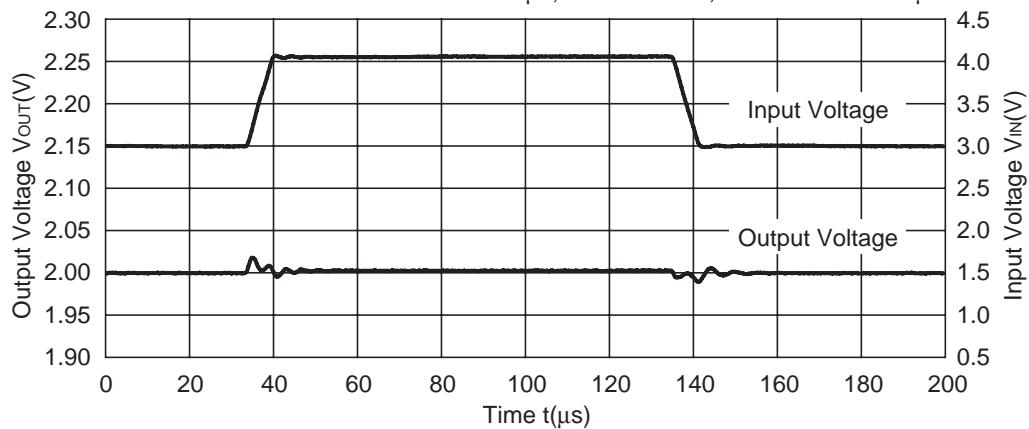
9) Ripple Rejection vs. Input Voltage**R1171x301x****R1171x301x****R1171x301x****R1171x301x****R1171x301x**

10) Input Transient Response ($T_{opt}=25^{\circ}\text{C}$)

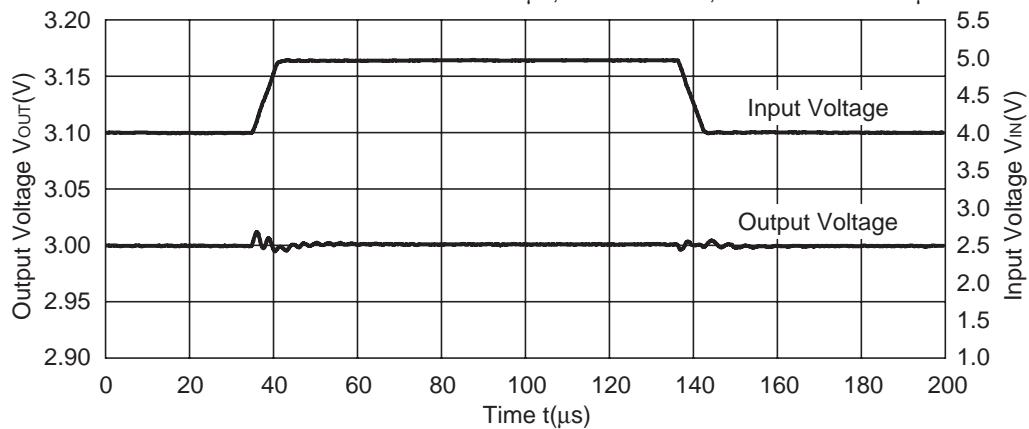
R1171x151B

 $\text{tr}=\text{tf}=5\mu\text{s}, \text{I}_{\text{OUT}}=1000\text{mA}, \text{C}_{\text{OUT}}=\text{Ceramic } 10\mu\text{F}$ 

R1171x201B

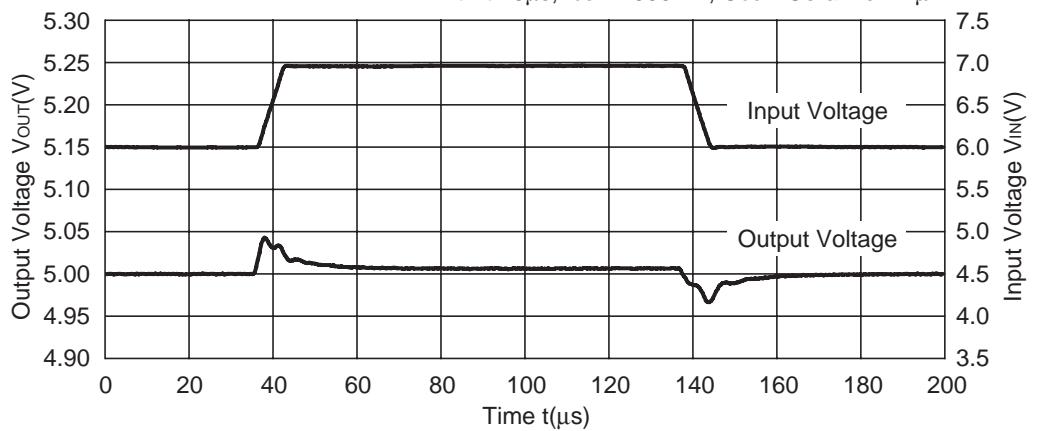
 $\text{tr}=\text{tf}=5\mu\text{s}, \text{I}_{\text{OUT}}=1000\text{mA}, \text{C}_{\text{OUT}}=\text{Ceramic } 4.7\mu\text{F}$ 

R1171x301B

 $\text{tr}=\text{tf}=5\mu\text{s}, \text{I}_{\text{OUT}}=1000\text{mA}, \text{C}_{\text{OUT}}=\text{Ceramic } 4.7\mu\text{F}$ 

R1171x501B

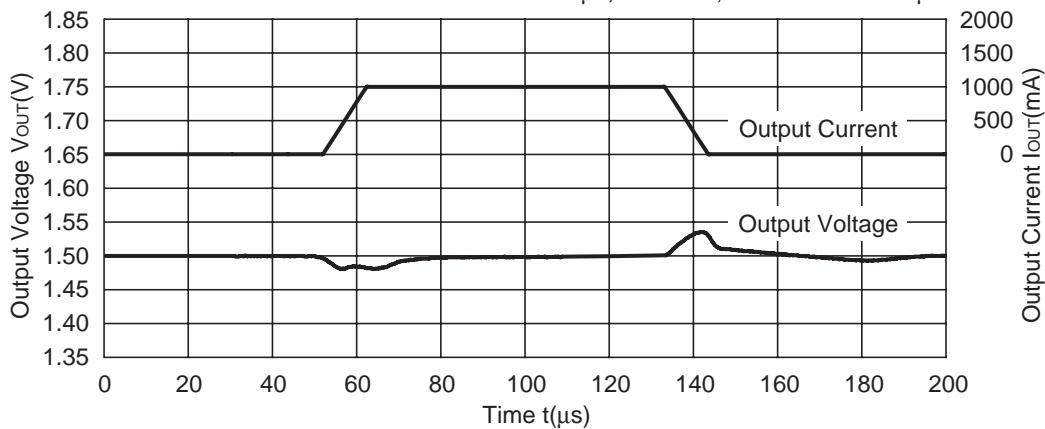
$t_r=t_f=5\mu s$, $I_{OUT}=1000mA$, $C_{OUT}=\text{Ceramic } 4.7\mu F$



11) Load Transient Response ($T_{OPT}=25^\circ C$)

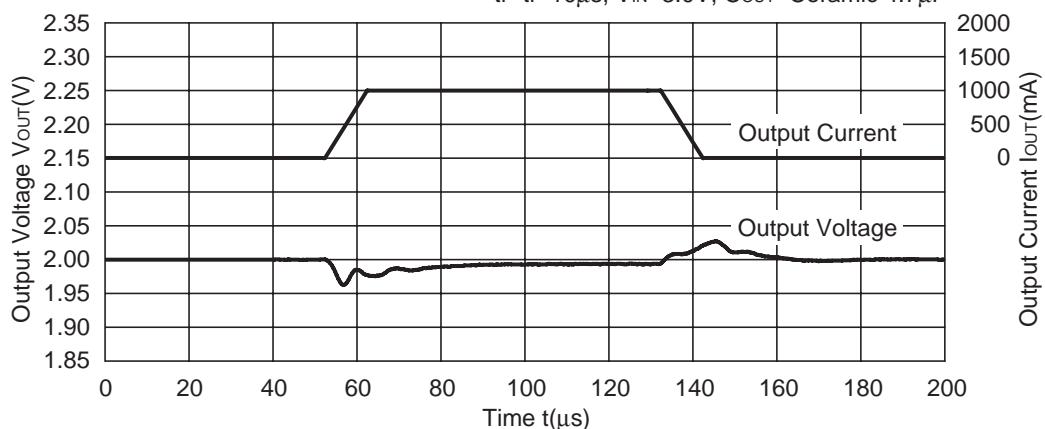
R1171x151B

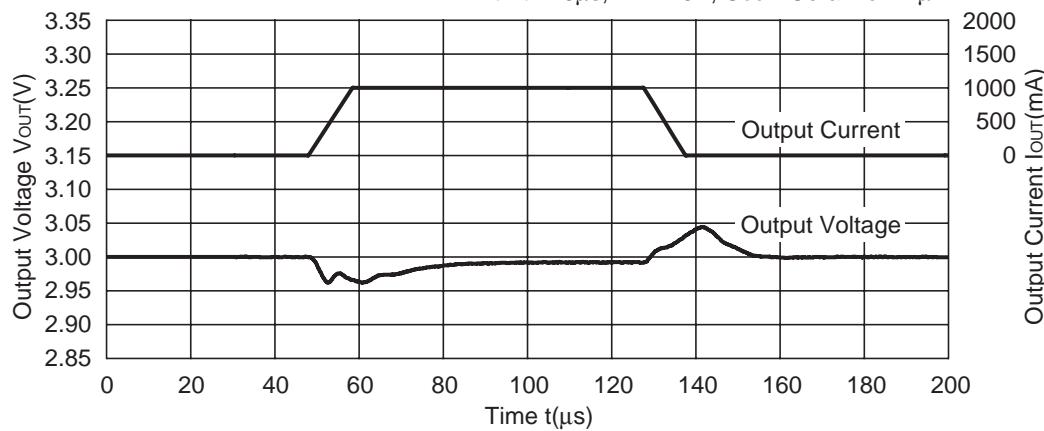
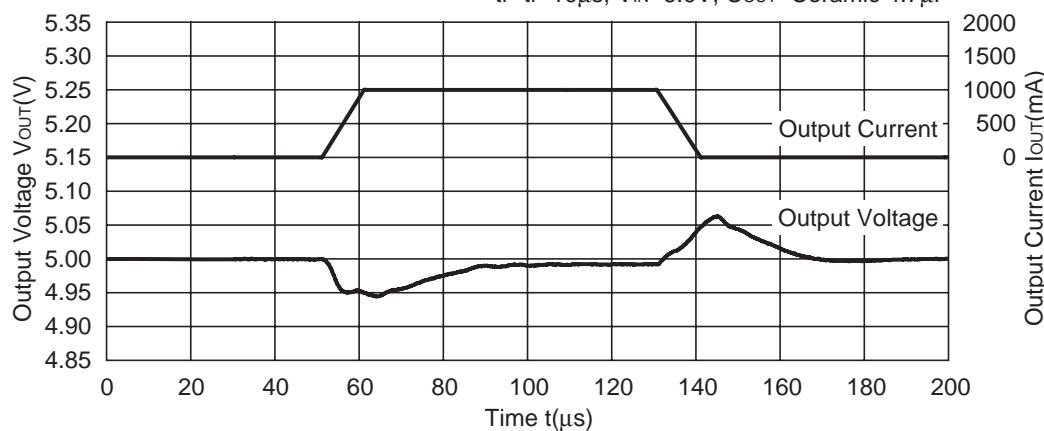
$t_r=t_f=10\mu s$, $V_{IN}=2.5V$, $C_{OUT}=\text{Ceramic } 10\mu F$



R1171x201B

$t_r=t_f=10\mu s$, $V_{IN}=3.0V$, $C_{OUT}=\text{Ceramic } 4.7\mu F$



R1171x301Btr=tf=10μs, V_{IN}=4.0V, C_{OUT}=Ceramic 4.7μF**R1171x501B**tr=tf=10μs, V_{IN}=6.0V, C_{OUT}=Ceramic 4.7μF

Technical Notes on External Components and Typical Application

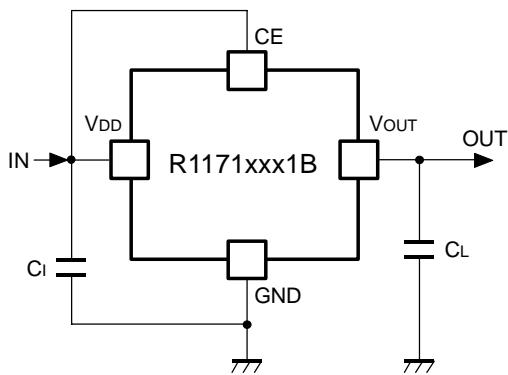
1. Phase Compensation

In these ICs, phase compensation is made with the output capacitor for securing stable operation even if the load current is varied. For this purpose, use a capacitor with the capacitance range from $4.7\mu\text{F}$ to $10.0\mu\text{F}$, as C_L . In case that using a tantalum capacitor and the ESR of the tantalum capacitor is too large, unstable operation may result. Fully evaluation is necessary for the whole circuit with considering the frequency characteristic.

2. Mounting on PCB

Make V_{DD} and GND lines sufficient. If their impedance is high, large current may flow and the pick-up noise or unstable operation may result. Therefore use a capacitor with a capacitance range from $4.7\mu\text{F}$ to $10.0\mu\text{F}$ between V_{DD} pin and GND pin as close as possible.

Further, set an output capacitor between V_{OUT} pin and GND pin for phase compensation as close as possible.
(Refer to the example of typical application)



R1171Sxx1B Typical Application

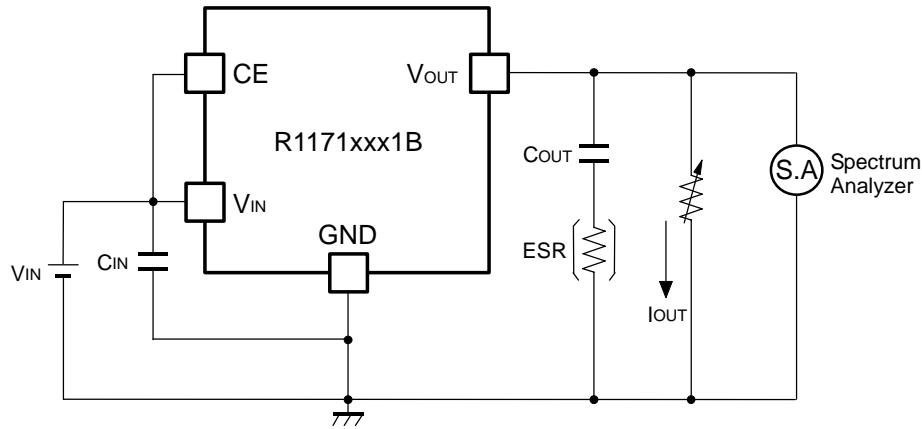
$1.5V \leq V_{OUT} < 1.8V : C_I = 10\mu\text{F}$ (Ceramic), $C_L = 10\mu\text{F}$ (Ceramic)

$1.8V \leq V_{OUT} \leq 5.0V : C_I = 4.7\mu\text{F}$ (Ceramic), $C_L = 4.7\mu\text{F}$ (Ceramic)

3. Output Short Protection Function

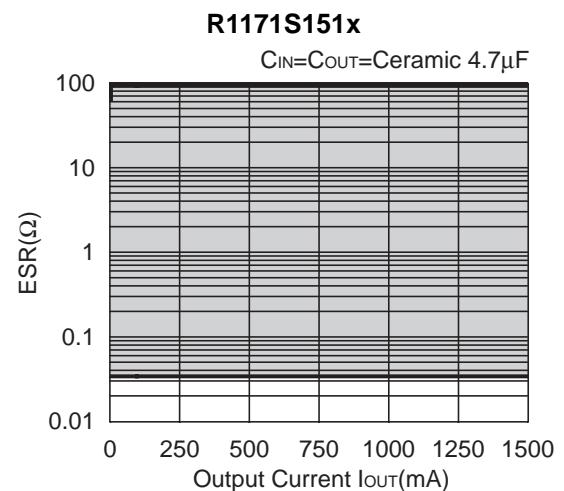
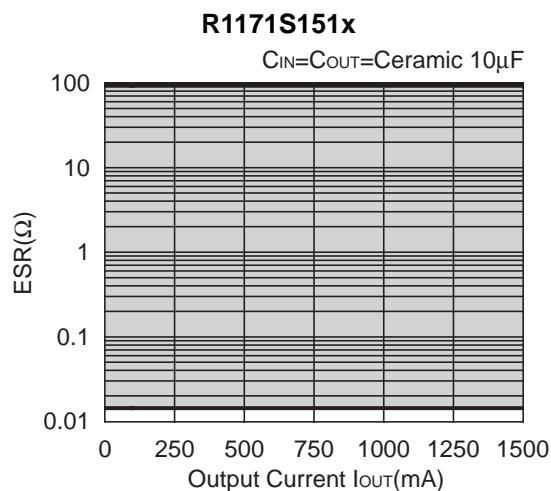
In the R1171x Series, the output short protection function is built in, further, if the output is short to the GND or other voltage line, the chip inside is heating, as a result, in case that the junction temperature becomes equal or more than 150°C (Typ.), the built-in thermal shutdown circuit works. If the junction temperature becomes equal or more than 150°C (Typ.), the IC is protected by the output short protection circuit and the thermal shutdown circuit.

ESR vs. Output Current ($T_{opt}=25^{\circ}\text{C}$, $V_{IN}=\text{Set Output Voltage}+1\text{V}$, $C_{IN}=\text{Ceramic } 10\mu\text{F}$)



As an output capacitor for this IC, Ceramic capacitor is recommendable. However, other low ESR type capacitor can be used with this IC.

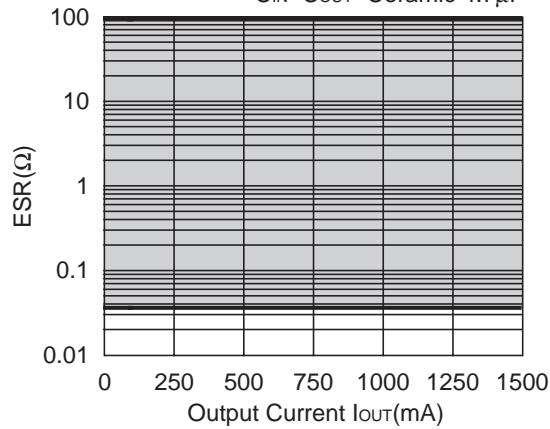
For your reference, noise level is tested with the circuit as shown above, and if the noise level is $40\mu\text{V}$ or less than $40\mu\text{V}$, the ESR values are plotted as stable area. Upper limit is described in the next four graphs, or ESR vs. Output Current. (Hatched area is the stable area.)



R1171x

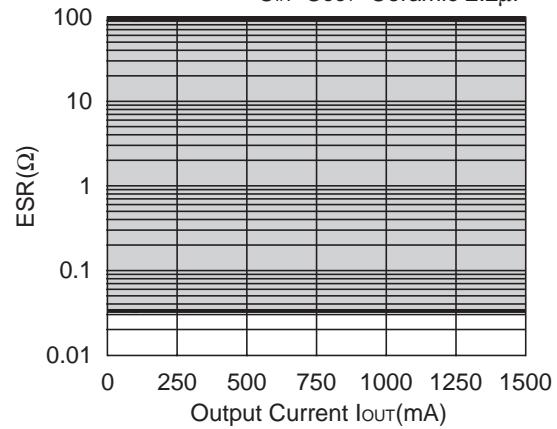
R1171S301x

$C_{IN}=C_{OUT}=\text{Ceramic } 4.7\mu\text{F}$



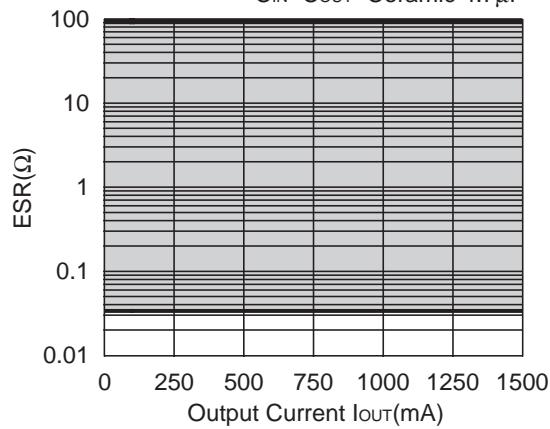
R1171S301x

$C_{IN}=C_{OUT}=\text{Ceramic } 2.2\mu\text{F}$



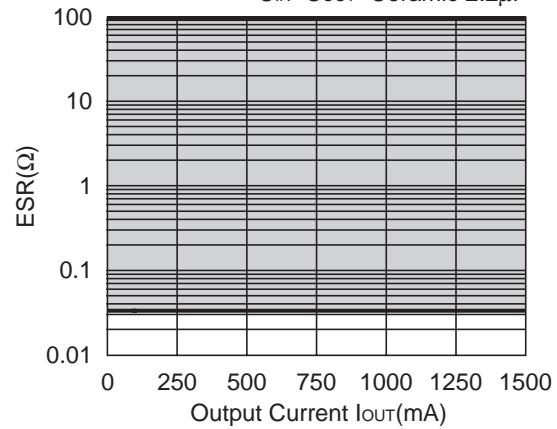
R1171S501x

$C_{IN}=C_{OUT}=\text{Ceramic } 4.7\mu\text{F}$



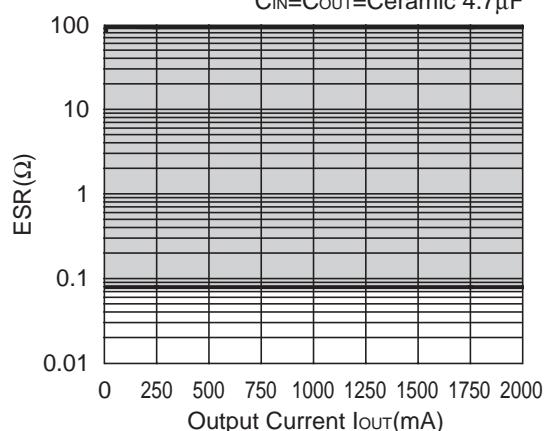
R1171S501x

$C_{IN}=C_{OUT}=\text{Ceramic } 2.2\mu\text{F}$



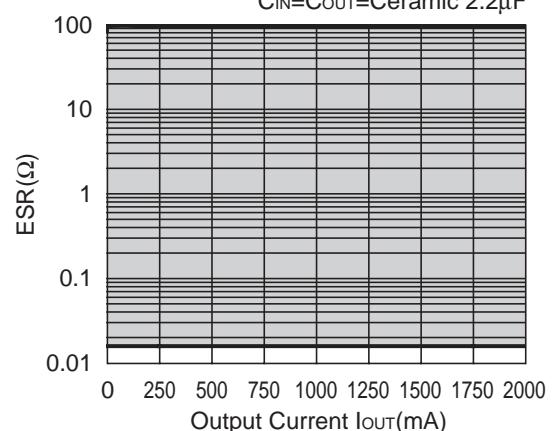
R1171J181x

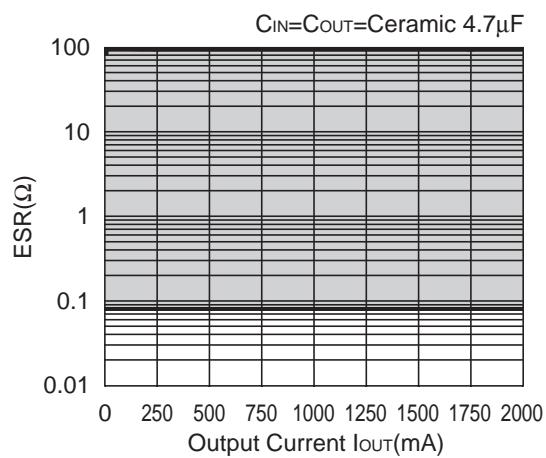
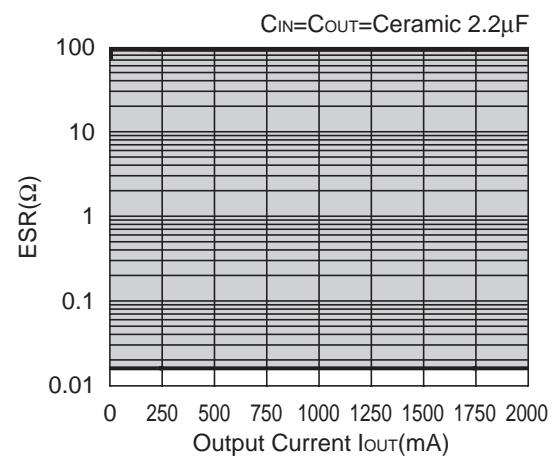
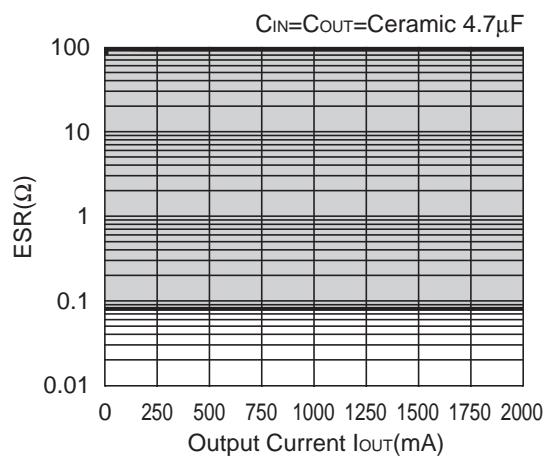
$C_{IN}=C_{OUT}=\text{Ceramic } 4.7\mu\text{F}$



R1171J181x

$C_{IN}=C_{OUT}=\text{Ceramic } 2.2\mu\text{F}$



R1171J301x**R1171J301x****R1171J501x****R1171J501x**